- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs
- Dependable Texas Instruments Quality and Reliability

#### description

These devices contain two independent 4-input positive NOR gates. They perform the Boolean functions:

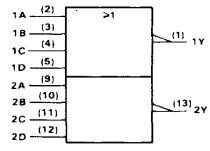
 $Y = \overline{A} + \overline{B} + \overline{C} + \overline{D}$  or  $Y = \overline{A} \cdot \overline{B} \cdot \overline{C} \cdot \overline{D}$  in positive logic.

The SN54HC4002 is characterized for operation over the full military temperature range of  $-55\,^{\circ}\text{C}$  to  $125\,^{\circ}\text{C}$ . The SN74HC4002 is characterized for operation from  $-40\,^{\circ}\text{C}$  to  $85\,^{\circ}\text{C}$ .

#### **FUNCTION TABLE**

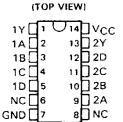
	INP	UTS		OUTPUT
A	В	С	D	[ Y
Н	Х	Х	Х	Ĺ.
X	Н	Х	Х	L
x	Х	н	X	l L
X	X	X	Н	L
L	L	L	L	н

#### logic symbol†

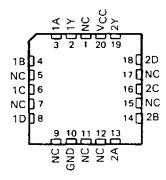


<sup>&</sup>lt;sup>†</sup>This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

SN54HC4002 . . . J PACKAGE SN74HC4002 . . . D OR N PACKAGE

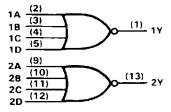


SN54HC4002 . . . FK PACKAGE (TOP VIEW)



NC-No internal connection

#### logic diagram (positive logic)



Pin numbers shown are for D, J, and N packages.

### absolute maximum ratings over operating free-air temperature range<sup>†</sup>

Supply voltage range, VCC0.5 V to 7 V
Input clamp current, IJK (VI < 0 or VI > VCC) ±20 mA
Output clamp current, IOK (VO < 0 or VO > VCC) ±20 mA
Continuous output current, IO (VO = 0 to VCC) ± 25 mA
Continuous current through VCC or GND pins ±50 mA
Lead temperature 1,6 mm (1/16 in) from case for 60 s: FK or J package
Lead temperature 1,6 mm (1/16 in) from case for 10 s; D or N package
Storage temperature range65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions

			SN54HC4002		SN74HC4002			UNIT	
			MIN	NOM	MAX	MIN	NOM	MAX	ONIT
Vcc	Supply voltage		2	5	6	2	5	6	>
		V <sub>CC</sub> = 2 V	1.5			1.5			
V <sub>IH</sub> High-level input voltage	High-level input voltage	$V_{CC} = 4.5 V$	3.15			3.15			٧
		V <sub>CC</sub> = 6 V	4.2			4.2			
		V <sub>CC</sub> = 2 V	0		0.3	0		0.3	
V <sub>IL</sub> Low-level input voltage	Low-level input voltage	V <sub>CC</sub> = 4.5 V	0		0.9	0		0.9	V
		V <sub>CC</sub> = 6 V	0		1.2	0		1.2	
V <sub>I</sub>	Input voltage		0		Vcc	0		V <sub>CC</sub> _	٧
Vo	Output voltage		0		VCC	0		VCC	V
		V <sub>CC</sub> = 2 V	0		1000	0		1000	
tt	Input transition (rise and fall) times	$V_{CC} = 4.5 \text{ V}$	0		500	0		500	กร
-		V <sub>CC</sub> = 6 V	0		400	0		400	
TΑ	Operating free-air temperature		- 55		125	-40		85	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		,,	TA = 25°C			SN54HC4002		SN74HC4002		UNIT
PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP	MAX	MIN	MAX	MIN	MAX	VIIII
		2 V	1.9	1.998		1.9		1.9		
1	$V_i = V_{iH}$ or $V_{IL}$ , $I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4		4.4		
∨o <sub>H</sub>		6 V	5.9	5.999		5.9	_	5.9		V
	$V_{I} = V_{IH}$ or $V_{IL}$ , $I_{OH} = -4$ mA	4.5 V	3.98	4.30		3.7		3.84		
	$V_{\parallel} = V_{\parallel H}$ or $V_{\parallel L}$ , $I_{OH} = -5.2$ mA	6 V	5.48	5.80		5.2		5.34		
		2 V		0.002	0.1		0.1		0.1	
	$V_1 = V_{IH}$ or $V_{IL}$ , $I_{OL} = 20 \mu A$	4.5 V		0.001	0.1		0.1	]	0.1	
VOL		6 V		0.001	0.1		0.1		0.1	V
	VI = VIH or VIL, IOL = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
1	VI = VIH or VIL, IOL = 5.2 mA	6 V		0.15	0.26		0.4		0.33	
- <sub>1</sub>	V <sub>I</sub> = V <sub>CC</sub> or 0	6 V		±0.1	±100		± 1000		1000	nΑ
<sup>l</sup> cc	$V_I = V_{CC}$ or 0, $I_{O} = 0$	6 V			2		40		20	μΑ
Ci		2 to 6 V		3	10	<u> </u>	10		10	pF

# switching characteristics over recommended operating free-air temperature range (unless otherwise noted), $C_L = 50 \text{ pF}$ (see Note 1)

DADAMETED	FROM	TO (OUTPUT)	Vcc	TA = 25°C			SN54HC4002		SN74HC4002		UNIT
PARAMETER	(INPUT)			MIN	TYP	MAX	MIN	MAX	MIN	MAX	ONL
			2 V		44	110		165		140	
t <sub>pd</sub>	A thru D	Y	4.5 V		12	22		33	ł	28	ns
			6 V		11	19		28		24	
		1	2 V		38	75		110		95	
tt		Y	4.5 V		8	15		22		19	ns
ŀ			6 V		6	13	ļ	19		16	

	<del> </del>	<del>,</del>	
C <sub>pd</sub>	Power dissipation capacitance per gate	No load, TA = 25°C	25 pF typ

Note 1: Load circuits and voltage waveforms are shown in Section 1.





i.com 26-Sep-2005

#### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
84044012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
8404401CA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/65104BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54HC4002J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN74HC4002N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SNJ54HC4002FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54HC4002J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC

<sup>&</sup>lt;sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### 14 LEADS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

#### FK (S-CQCC-N\*\*)

#### **28 TERMINAL SHOWN**

#### **LEADLESS CERAMIC CHIP CARRIER**



NOTES: A. All linear dimensions are in inches (millimeters).

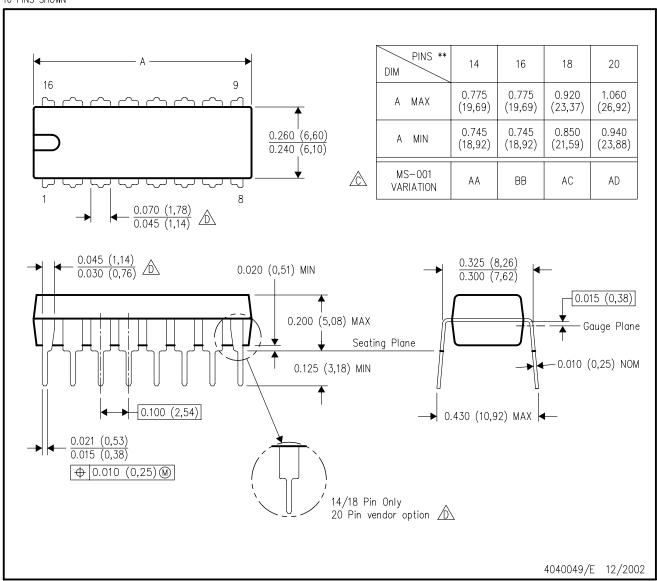
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



## N (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



#### **IMPORTANT NOTICE**

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

Copyright © 2005, Texas Instruments Incorporated